



Material Content Data Sheet



Sales Product Name		BSS606N H6327		Issued		9. January 2019		
MA#		MA001047560						
Package		PG-SOT89-4-2		Weight*		50.62 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.006	0.01		116	
	noble metal	gold	7440-57-5	0.023	0.04		450	
	inorganic material	silicon	7440-21-3	0.347	0.69	0.74	6863	7429
leadframe	inorganic material	silicon	7440-21-3	0.004	0.01		85	
	non noble metal	titanium	7440-32-6	0.022	0.04		427	
	non noble metal	chromium	7440-47-3	0.065	0.13		1281	
	non noble metal	copper	7440-50-8	21.522	42.51	42.69	425141	426934
wire	non noble metal	copper	7440-50-8	0.064	0.13	0.13	1272	1272
encapsulation	organic material	carbon black	1333-86-4	0.274	0.54		5416	
	plastics	epoxy resin	-	4.112	8.12		81234	
	inorganic material	silicondioxide	60676-86-0	23.029	45.50	54.16	454911	541561
leadfinish	non noble metal	tin	7440-31-5	0.801	1.58	1.58	15829	15829
plating	noble metal	silver	7440-22-4	0.353	0.70	0.70	6975	6975
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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